
Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2. del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB (IEC 62680-1-2:2026)

Universal Serial Bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2026)

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2: Gemeinsame Komponenten - USB Stromversorgungs-Spezifikation (IEC 62680-1-2:2026)

Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification de l'alimentation électrique par port USB (IEC 62680-1-2:2026)

Ta slovenski standard je istoveten z: EN IEC 62680-1-2:2026

ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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SIST EN IEC 62680-1-2:2026

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 62680-1-2

March 2026

ICS 29.220; 33.120; 35.200

Supersedes EN IEC 62680-1-2:2025

English Version

**Universal Serial Bus interfaces for data and power - Part 1-2:
Common components - USB Power Delivery specification
(IEC 62680-1-2:2026)**

Interfaces de bus universel en série pour les données et
l'alimentation électrique - Partie 1-2: Composants communs
- Spécification de l'alimentation électrique par port USB
(IEC 62680-1-2:2026)

Schnittstellen des Universellen Seriellen Busses für Daten
und Energie - Teil 1-2: Gemeinsame Komponenten - USB
Stromversorgungs-Spezifikation (IEC 62680-1-2:2026)

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EN IEC 62680-1-2:2026 (E)**European foreword**

The text of document 100/4327/CDV, future edition 8 of IEC 62680-1-2, prepared by TC 100/Technical Area 18 "(Disbanded) - Multimedia home systems and applications for end-user networks" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2026.

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IEC 62680-1-2

Edition 8.0 2026-02

INTERNATIONAL STANDARD

**Universal Serial Bus interfaces for data and power -
Part 1-2: Common components - USB Power Delivery specification**

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Universal Serial Bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

Draft	Report on voting
100/4327/CDV	100/4380/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

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Universal Serial Bus

Power Delivery Specification

Revision: **3.2**

Version: **1.1**

Release Date: **2024-10**

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Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
2.0	1.2	Including errata through 25-March-2016	25 March 2016
2.0	1.3	Including errata through 11-January-2017	11 January 2017
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.1	Including errata through 12-January-2017	12 January 2017
3.0	1.2	Including errata through 21-June-2018	21 June 2018
3.0	2.0	Including errata through 29-August-2019	29 August 2019
3.1	1.0	Including errata through May 2021	May 2021
3.1	1.1	Including errata through July 2021 This version incorporates the following ECNs: - EPR Clarifications - Define AMS starting point	July 2021
3.1	1.2	Including errata through October 2021 This version incorporates the following ECNs: - Clarify use of Retries - Battery Capabilities - FRS timing problem - PPS power rule clarifications - Peak current support for EPR AVS APDO	October 2021
3.1	1.3	This version incorporates the following ECNs: - Robust EPR Source Operation - EPR Source Caps Editorial - SRC PPS behavior in low current request - Enter USB	January 2022
3.1	1.4	Editorial changes This version incorporates the following ECNs: - Capabilities Mismatch Update - Chunking Timing Issue - OT Mitigation	April 2022

Revision	Version	Comments	Issue Date
3.1	1.5	Editorial changes This version incorporates the following ECNs: • Timer Description Corrections • Change Source_Info Requirements • AMS Update	July 2022
3.1	1.6	Editorial changes This version incorporates the following ECNs: • USB4® V2 Updates • Data Reset Issues • Increase tSenderResponse • PPS Power Limit Bit Update • Support for Asymmetric Mode • Timer Description Corrections Revisited	October 2022
3.1	1.7	Editorial Changes This version incorporates the following ECNs: • Data Reset Invalid Reject Handling • Source request • Source Transition • EPR Entry	January 2023
3.1	1.8	Editorial Changes This version incorporates the following ECNs: • Slew rate exemption for Power Role Swap. • EUDO cable speed clarification. • Update to PPS Requirements. • Deprecate Interruptibility. • Section 7.3 restructure and update.	April 2023
3.1	1.9	Editorial Changes	July 2023

Revision	Version	Comments	Issue Date
3.2	1.0	This version incorporates the following ECNs: • VDM-use Conditions. • tTypeCSinkWaitCap. • tFirstSourceCap Clarification • Hard Reset Clarification. • Unrecognized Country Code • EPR Entry Process-1 • SPR AVS Definition • EPR Power Rules Clarifications	October 2023
3.2	1.1	This version incorporates the following ECNs: • Power Transition time from EPR to PR_Swap • Capabilities Mismatch Update • Deprecate GotoMin and GiveBack Features and Update Power Reserve • EPR Entry requirements Clarification • EPRMDO and Entry Clarification. • Remove 10.2.4 power sharing between ports • Source PDP rating field clarifications • Source Power Rules update. • Source_Info Message Clarifications. • Correction to BMC description. • EPR Source cap clarification. • Delaying of VCONN Swap. • EPR_Request in SPR Mode. • Generic transition diagram. • Removing the usage of Ping message • Sink Standby • Source Info Support	October 2024

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